CERVOZ

Making Memories for Industry

Anti-Vibration Fill

Industrial DRAM Module

Anti-Vibration Fill
to Enhance Cost Effective Solution

In real-world industrial computing applications, more and smaller embedded devices are installed in harsh environments with constant shock or vibrations. The DRAM modules inside these devices may be vulnerable to these impacts, causing poor contacts and connection.

Cervoz offers a value-added service " Anti-Vibration Fill " to enhance the robustness of our all DRAM modules to prevent the solder joints from coming loose.

Anti-Vibration Fill provides extra endurance for DRAM modules installed in machine automation, in-vehicle computing, military, outdoor and industrial critical environment applications.

Machine Automation

In-vehicle Computing

Military

Outdoor

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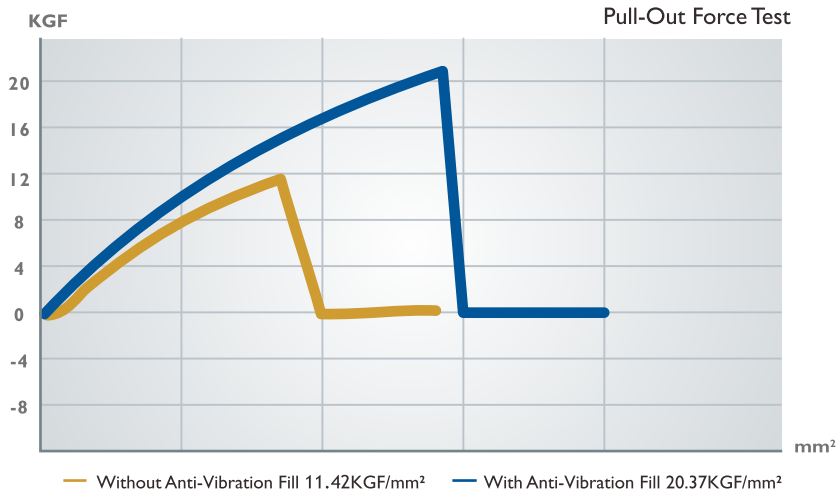
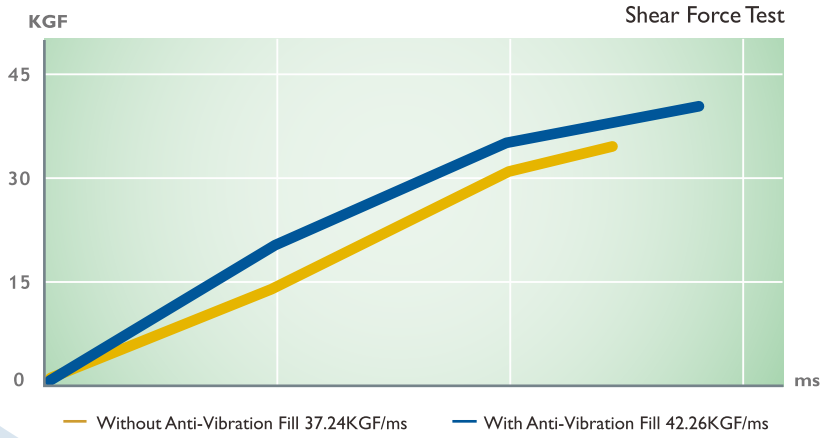
Product Highlights

The third party Lab has verified the resistance against the pull-out force and shear force will be increased when the product has Anti-Vibration Fill, the test as below.



*The resistance against the pull-out force will be **double***



*The resistance against the shear force will be **increased 15%***

Related Products

Anti-Vibration Fill is available for Cervoz Industrial DRAM Module.

- Standard Series (0°C~70°C)
- Wide Temperature Series (-40°C~85°C)
- Server Series :
  - DIMM with ECC and ECC with Registered
  - SO-DIMM with ECC

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